

RB521S30T1G, NSVRB521S30T1G, RB521S30T5G



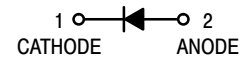
ON Semiconductor®

<http://onsemi.com>

30 V SCHOTTKY BARRIER DIODE



**SOD-523
CASE 502**



MARKING DIAGRAM



5M = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

Schottky Barrier Diode

These Schottky barrier diodes are designed for high-speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage 0.5 V (max) @ $I_F = 200$ mA
- Low Reverse Current
- AEC Qualified and PPAP Capable
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|-----------|-------|------|
| Reverse Voltage | V_R | 30 | Vdc |
| Forward Current DC | I_F | 200 | mA |
| Peak Forward Surge Current (Note 1) | I_{FSM} | 1.0 | A |
| ESD Rating: Class 1C per Human Body Model Class C per Machine Model | | | |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. 60 Hz for 1 cycle.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------|-------------|----------------------------|
| Total Device Dissipation FR-5 Board, (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 200 1.57 | mW mW/ $^\circ\text{C}$ |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 635 | $^\circ\text{C}/\text{W}$ |
| Junction and Storage Temperature Range | T_J, T_{stg} | -55 to +125 | $^\circ\text{C}$ |

2. FR-5 Minimum Pad.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|----------------|-------------------|---------------------------------|
| RB521S30T1G | SOD-523 (Pb-Free) | 4 mm Pitch 3,000/Tape & Reel |
| NSVRB521S30T1G | SOD-523 (Pb-Free) | 4 mm Pitch 3,000/Tape & Reel |
| RB521S30T5G | SOD-523 (Pb-Free) | 2 mm Pitch 8,000/Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|--------|-----|-----|------|---------------|
| Reverse Leakage ($V_R = 10\text{ V}$) | I_R | - | - | 30.0 | μA |
| Forward Voltage ($I_F = 200\text{ mA}$) | V_F | - | - | 0.50 | Vdc |

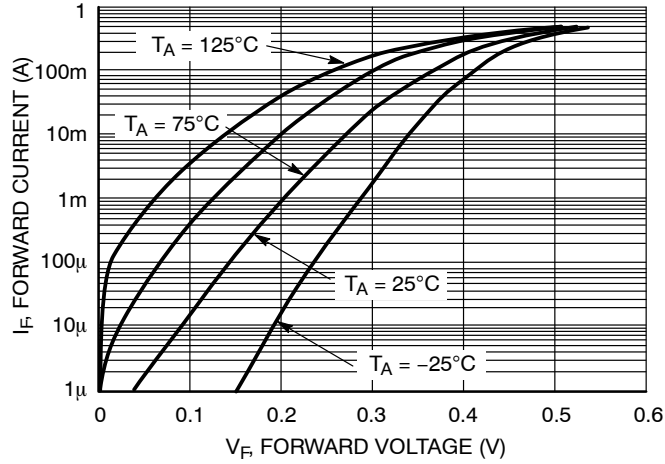


Figure 1. Forward Characteristics

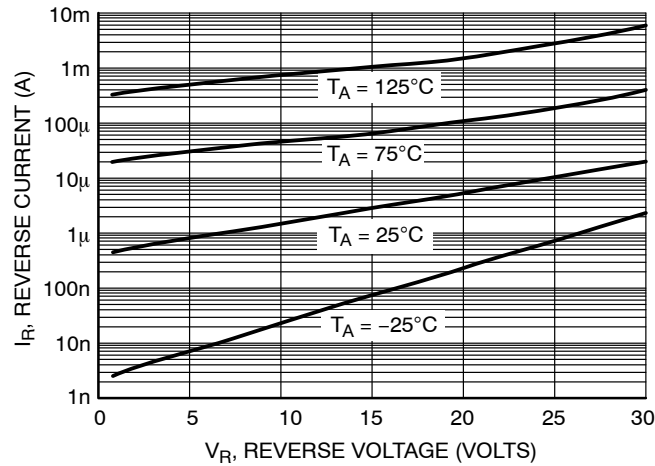


Figure 2. Reverse Characteristics

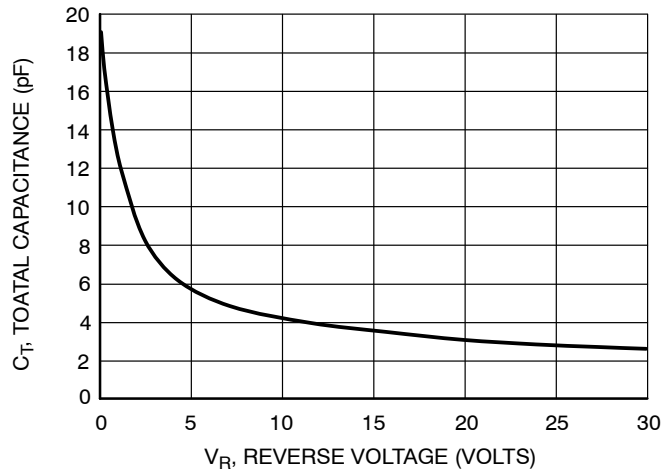
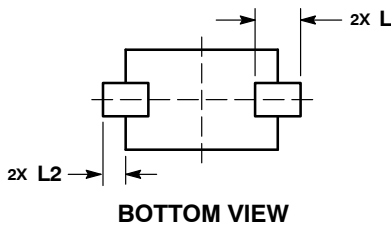
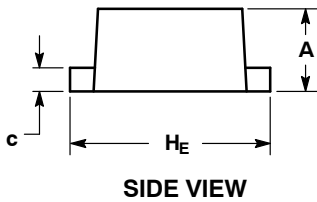
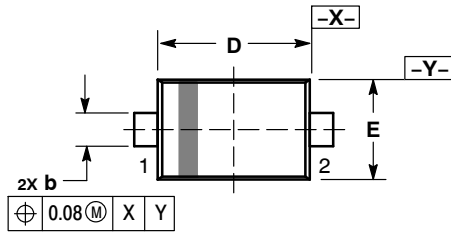


Figure 3. Total Capacitance

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PACKAGE DIMENSIONS

SOD-523
CASE 502-01
ISSUE E

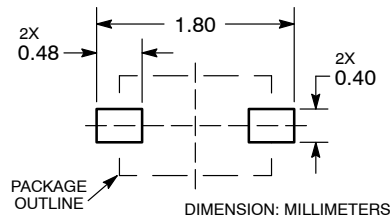


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN | NOM | MAX |
| A | 0.50 | 0.60 | 0.70 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.07 | 0.14 | 0.20 |
| D | 1.10 | 1.20 | 1.30 |
| E | 0.70 | 0.80 | 0.90 |
| HE | 1.50 | 1.60 | 1.70 |
| L | 0.30 REF | | |
| L2 | 0.15 | 0.20 | 0.25 |

- STYLE 1:
PIN 1. CATHODE (POLARITY BAND)
2. ANODE

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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- Защита от снятия компонента с производства.



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